

Dual N-Channel 250V Enhancement Mode MOSFETs

Marking

25N35DHVT

General Features

- Proprietary Advanced Planar Technology
- Rugged Polysilicon Gate Cell Structure
- Proprietary Advanced High Vth Technology
- RoHS Compliant

Part Number

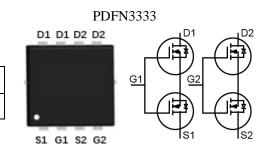
FTF25N35DHVT

Halogen-free available

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Absolute Maximum Ratings

BV _{DSS}	RDS(ON) (Max.)	Id
250V	25 Ω	0.9A



Package

PDFN3333

 $T_A=25^{\circ}C$ unless otherwise specified

Symbol	Parameter	FTF25N35DHVT	Unit		
V _{DSS}	Drain-to-Source Voltage ^[1]	250	V		
ID	Continuous Drain Current	0.9			
I _{DM}	Pulsed Drain Current ^[2]	3.6	A		
P _D	Power Dissipation	16	W		
V _{GS}	Gate-to-Source Voltage	±20	V		
T_L	Soldering Temperature Distance of 1.6mm from case for 10 seconds	300	°C		
$T_{\rm J}$ and $T_{\rm STG}$	Operating and Storage Temperature Range	-55 to 150			

Remark

Halogen Free

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

Thermal Characteristics

Symbol	Parameter	FTF25N35DHVT	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	34	K/W



Electrical Characteristics

OFF Characteristics

OFF Characteristics					$T_A = 25^{\circ}C$ unless otherwise specified		
Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions	
BV _{DSS}	Drain-to-Source Breakdown Voltage	250			V	V _{GS} =0V, I _D =250µA	
I _{DSS}	Drain-to-Source Leakage Current			1	μΑ	$V_{DS}=250V$, $V_{GS}=0V$	
				100	μΑ	$V_{DS}=250V, V_{GS}=0V$ $T_{J}=125^{\circ}C$	
I _{GSS}	Gate-to-Source Leakage Current			1	μA	V_{GS} =+20V, V_{DS} =0V	
				-1		V_{GS} =-20V, V_{DS} =0V	

ON Characteristics

 $T_A = 25 \,^{\circ}C$ unless otherwise specified

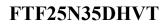
Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
R _{DS(ON)}	Static Drain-to-Source On-Resistance		12	25	Ω	V_{GS} =10V, I_D =100mA ^[3]
V _{GS(TH)}	Gate Threshold Voltage	2		5	V	$V_{GD} = 0V, I_D = 250 \mu A$
V _{GS(TH)_REV}	Reverse Gate Threshold Voltage	5		10	V	$V_{GS} = 0V, I_D = -5\mu A$

NOTE:

[1] T_J=+25°C to +150°C

[2] Repetitive rating, pulse width limited by maximum junction temperature.

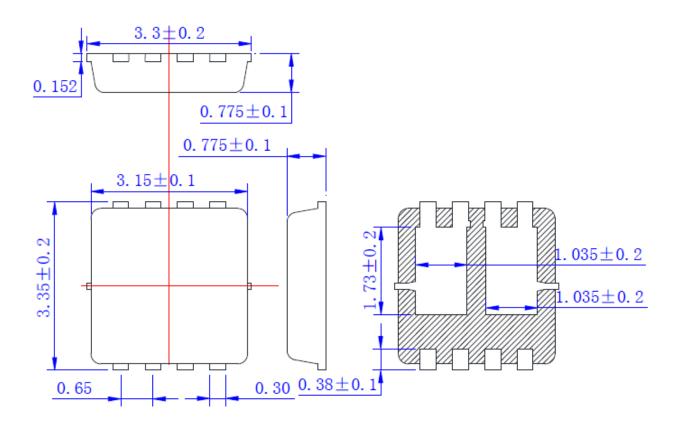
[3] Pulse width \leq 380µs; duty cycle \leq 2%.





Package Dimensions

PDFN3333



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